



# 1.5 Micron CMOS Process Family

February 1996

## Features

- LO<sub>V</sub>MOS Processes (2.7~3.6 Volts Low Voltage Option)
- 1.2 Volts Very Low Voltage Option
- 5.5 Volts Maximum Operating Voltage
- Double Poly / Double Metal
- 3 μm Poly and Metal I Pitch
- ProToDuction™ Option for prototypes

## Description

The 1.5μm process provides flexibility, speed and packing density needed in mixed signal designs. The aggressive design rules make it comparable to most 1.2 μm processes. A 3 volts and a 1.2 volts options are also available for low voltage applications, they offer low and matched threshold voltages for improved dynamic range.

## Technology Outline

- Drain Engineered Structure to Ensure Reliability against Hot-Carrier Injection
- Planarization with SOG Sandwich Structure
- Nitride Passivation for Reliability against Moisture
- Latchup Free Process on Non-Epi Material Achieved with Optimized I/O Protection

## Process Parameters

Process Parameters	1.5μm	Units
Metal I pitch (width/space)	1.5 / 1.5	μm
Metal II pitch (width/space)	2.0 / 1.8	μm
Poly pitch (width/space)	1.5 / 1.5	μm
Contact	1.5 x 1.5	μm
Via	1.8 x 1.8	μm
Gate geometry	1.5	μm
P-well junction depth	3.0	μm
N+ junction depth (5V& 3V/1.2V)	0.28 / 0.20	μm
P+ junction depth	0.28	μm
Gate oxide thickness	270	Å
Inter poly oxide thick.	480	Å

## MOSFET Electrical Parameters

	1.5 MICRON - 1.2 volts			1.5 MICRON - 3 volts			1.5 MICRON - 5 volts			Units	Conditions
	N Channel min. typ. max.	P Channel min. typ. max.		N Channel min. typ. max.	P Channel min. typ. max.		N Channel min. typ. max.	P Channel min. typ. max.			
V <sub>t</sub> (50x1.5μm)	0.30 0.40 0.50	0.30 0.40 0.50		0.35 0.50 0.65	0.35 0.50 0.65		0.55 0.70 0.85	0.55 0.70 0.85		V	Saturation
I <sub>ds</sub> (50x1.5μm)	13	5.5		14	6		9.8 12.0	3.9 5.0		mA	V <sub>ds</sub> =V <sub>gs</sub> =5V
Gain β (50x1.5μm)	2.92	1.05		3.50	1.05		2.90	0.80		mA/V <sup>2</sup>	Linear (1.2V&3.0V) Saturation (5V)
Body Factor (50x50μm)	0.50	0.77		0.52	0.75		0.45	0.81		√V	
B <sub>vdss</sub> (50x1.5μm)	5 10	5 9		7 12	7 12		10 12	10 12		V	I <sub>ds</sub> =20nA
Subthreshold Slope	85	105		87	106		93	101		mV/dec.	V <sub>ds</sub> =0.1V
Substrate Current	1.1	NA		0.26	NA		0.21	NA		μA/μm	V <sub>ds</sub> =5.5V, V <sub>gs</sub> =2.3V
Field Threshold	10 15	10 14		10 15	10 14		10 17	10 20		V	I <sub>ds</sub> = 1μA/square
L Effective	1.27	1.12		1.09	1.05		1.2	1.2		μm	L <sub>drawn</sub> = 1.5μm
Gate Propagation Delay Propagation Delay Time per Stage (47 Stage Ring Oscillator)	Typ. = 2.4 ns @1.2V			Typ. = 530 ps @3.3V			Typ. = 380 ps @5.0V				P 6.3/1.5 N 2.3/1.5

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## Capacitances (fF/ $\mu\text{m}^2$ )

	1.5 $\mu\text{m}$		
	min.	typ.	max.
Inter-poly	0.62	0.72	0.84
Gate oxide	1.3		
N+ Junction	0.29		
P+ Junction	0.27		

## Resistances ( $\Omega/\text{sq.}$ )

	1.5 $\mu\text{m}$		
	min.	typ.	max.
Pwell	5700		
Pfield in Pwell	2600	3000	3400
N+	30	40	50
P+	70	90	110
Poly gate	15	20	25
Poly capacitor	75	100	125
Metal I	0.038		
Metal II	0.038		

## Bipolar gain<sup>1</sup>

	1.5 $\mu\text{m}$ - 5 volts		
	min.	typ.	max.
NPN vertical	180		

<sup>1</sup>Test condition : Vce = 5 volts

FIG 1 : I-V Characteristics for a 10x1.5 $\mu\text{m}$  N-MOSFET (1.5 $\mu\text{m}$  5 volts process)

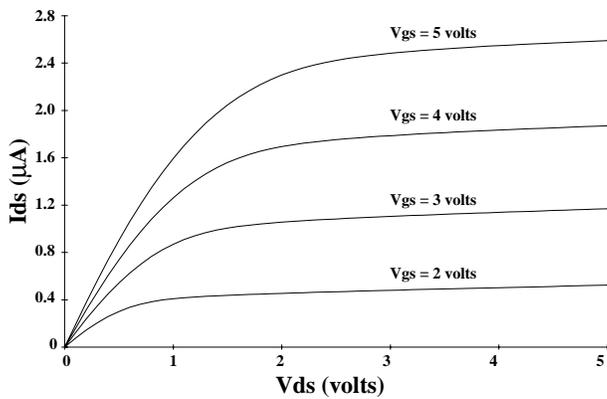


FIG 2 : I-V Characteristics for a 10x1.5 $\mu\text{m}$  P-MOSFET (1.5 $\mu\text{m}$  5 volts process)

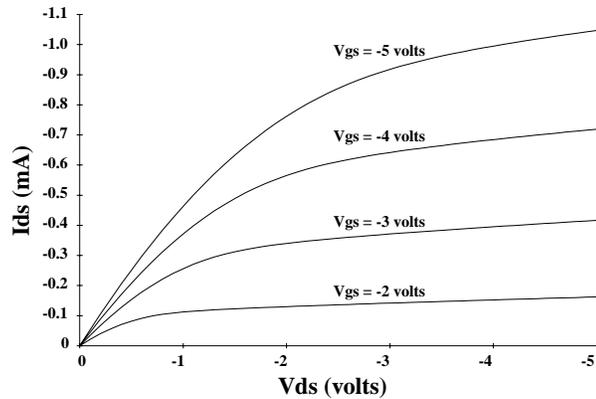


FIG 3 : Subthreshold Characteristics at Vds=0.1 volt for a 10x1.5 $\mu\text{m}$  N-MOSFET (1.5 $\mu\text{m}$  5 volts process)

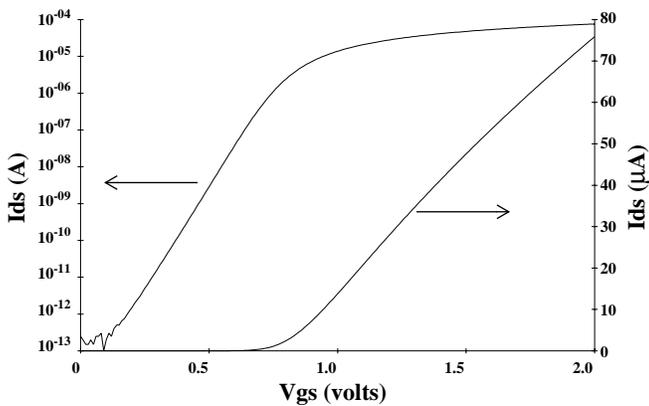


FIG 4 : Subthreshold Characteristics at Vds=-0.1 volt for a 10x1.5 $\mu\text{m}$  P-MOSFET (1.5 $\mu\text{m}$  5 volts process)

